

CLAIMS

- ✓ 1. A connecting material for bonding and connecting a semiconductor chip with the substrate glass board in a COG assembly, in which the electrodes of the semiconductor chip are held in a direct connection with the corresponding electrodes on the substrate glass board, the said connecting material comprising
an adhesive component comprising a thermosetting resin and
electroconductive particles,
wherein the said material has, after having been cured, a tensile elongation percentage at 25 °C of at least 5 %.
2. The connecting material as claimed in claim 1, wherein the adhesive component comprises 6 - 90 % by weight of a microparticulate elastomer having an average particle size of 30 - 300 nm.
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- a 3. The connecting material as claimed in claim 1 or 2, wherein it comprises 2 - 40 %, based on the volume of the adhesive component, of the electroconductive particles.
4. A COG assembly, in which the electrodes of a semiconductor chip are held in a direct connection with the corresponding electrodes on the substrate glass board, comprising
a layer of a connecting material for bonding and connecting the semiconductor chip with the substrate board,
wherein the said material comprises an adhesive

component comprising a thermosetting resin and electroconductive particles and has after having been cured, a tensile elongation percentage at 25 °C of at least 5 %.

5. The COG assembly as claimed in claim 4, wherein the adhesive component comprises 6 - 90 % by weight of a microparticulate elastomer having an average particle size of 30 - 300 nm.

a 6. The COG assembly as claimed in claim 4 or 5, wherein the connecting material comprises 2 - 40 %, based on the volume of the adhesive component, of the electroconductive particles.

a 7. The COG assembly as claimed in any one of claims 4 to 6, wherein the COG assembly is a liquid crystal display.

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